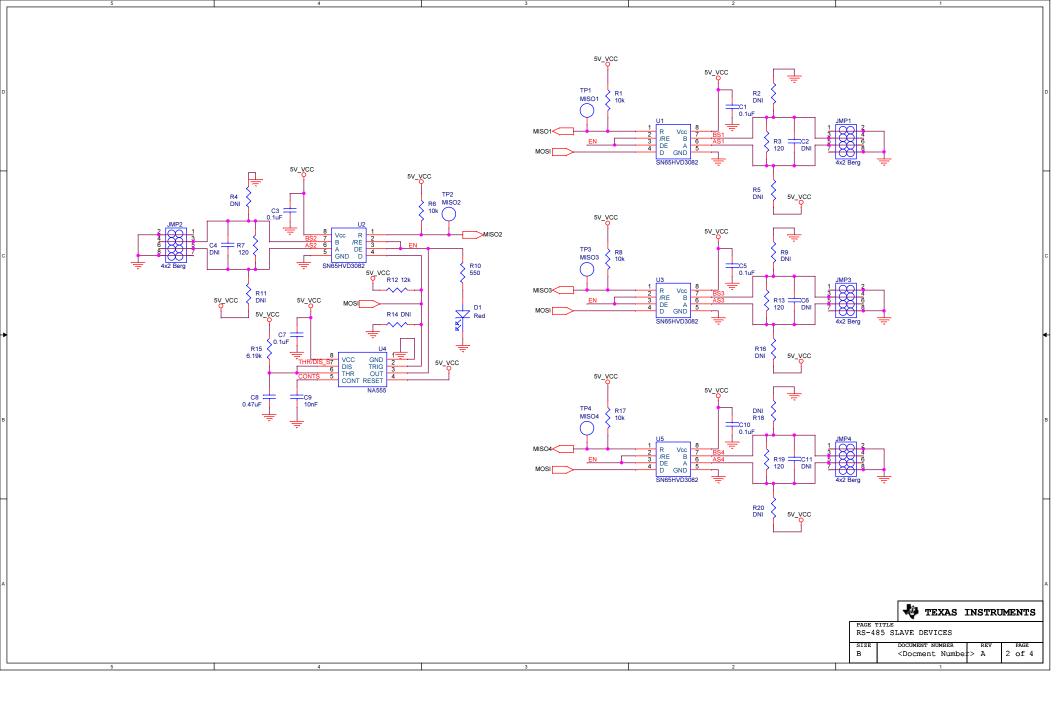
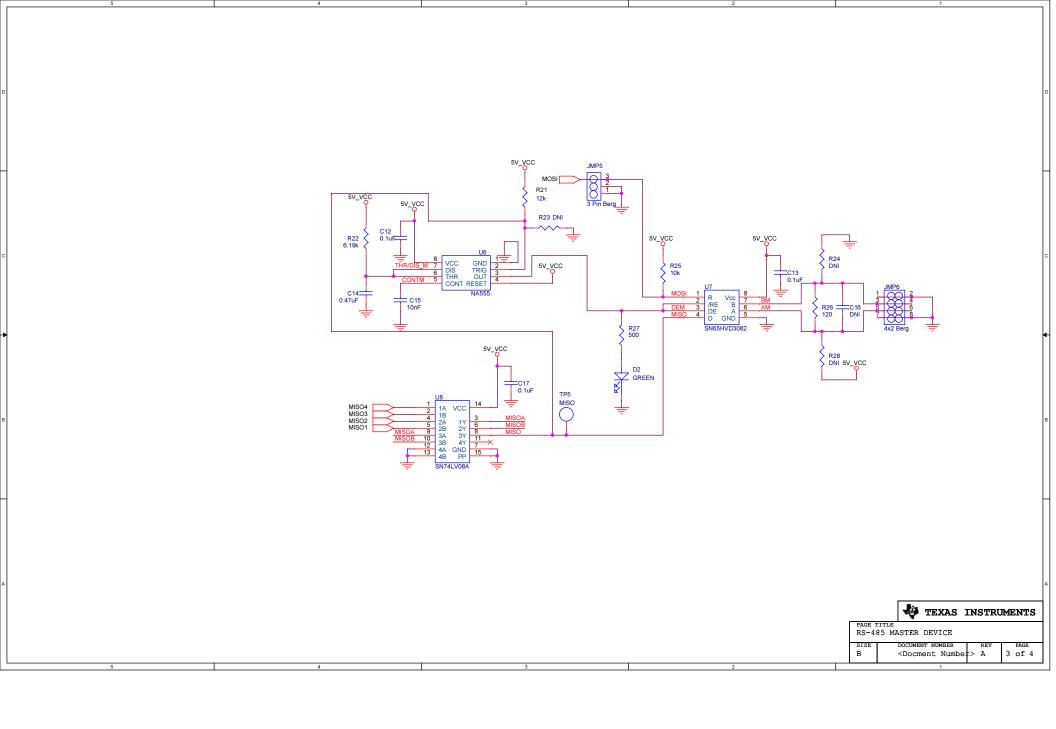
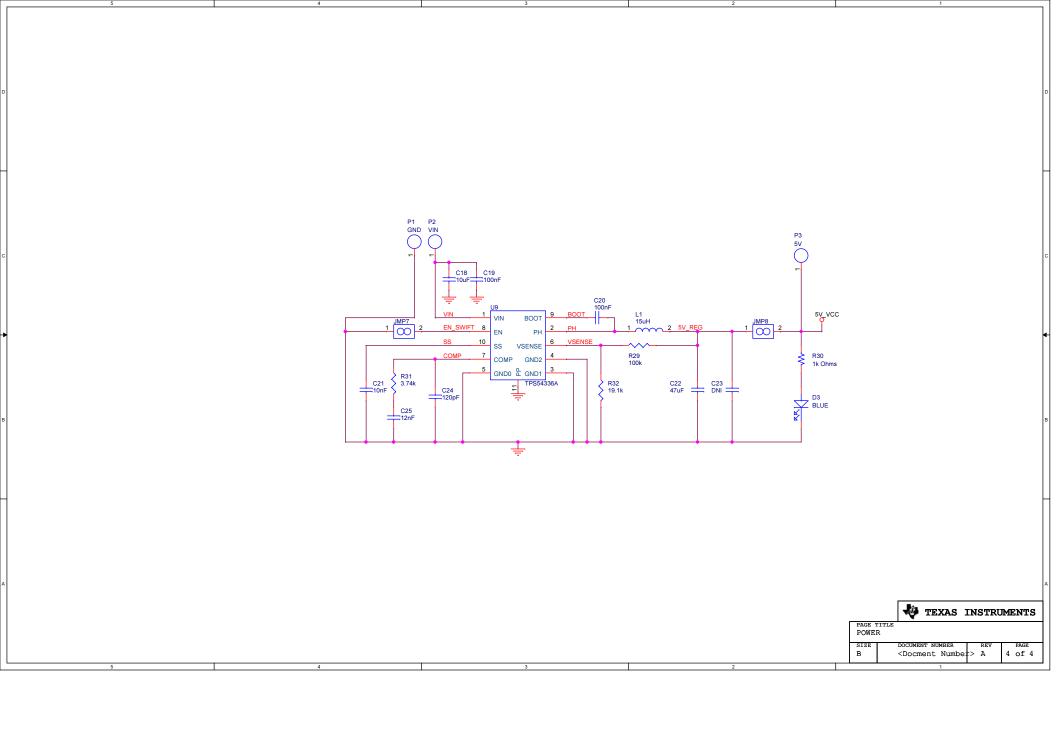
	5	4	3		2	1 REVISION	10
NOTES:						ECR <ecr></ecr>	DATE <date></date>
1. PI	LACE NET NAMES ON ALL JUMPERS AND	HEADERS. NECTORS ON A 0, 45 OR 90 DEGREE OF	PIENTATION				
3. SE	ERIAL DATA SHOULD BE ROUTED AS 60	OHMS SINGLE ENDED. ROUTED POWER S	SHOULD BE A MINIMUM OF 40 MILS WID	Ε.			
4. US	SE FR4-370 MATERIAL FOR ALL LAYER	5.					
D 5. PI 6. SF	LACE TI LOGO, BOARD NAME, AND THE EE ADDITIONAL NOTES IN SCHEMATIC	BOARD NUMBER IN TOP SIDE METAL.					
		0.011					
c		SCH	EMATIC SHEET	INDEX:			
			5 FAN-OUT HUB COVER SHEET ANI	NOTES			
		SHEET 02: RS-485					
		SHEET 03: RS-485 SHEET 04: POWER	MASTER DEVICE				
		SHEET 04: POWER					
*							1
8							
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						'EXAS INSTRUN	MENTS
A						HEMATIC TITLE DA-01365	
					ENGINEER DATE	DA-01365 -485 FAN OUT HUB	
					MICHAEL PEFFERS 11/21/2016	GE TITLE	
					LAYOUT DATE CO	OVER PAGE AND NOTES	
SN65H	/D1040 DATA SHEET REVISION: x.x. SHEET LAST UPDATED ON: xx/xx/xx	x			KRYPTON 11/21/2016		
					RELEASED DATE SIZ MICHAEL PEFFERS 11/21/2016 B		REV SHEET A 1 of 4
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